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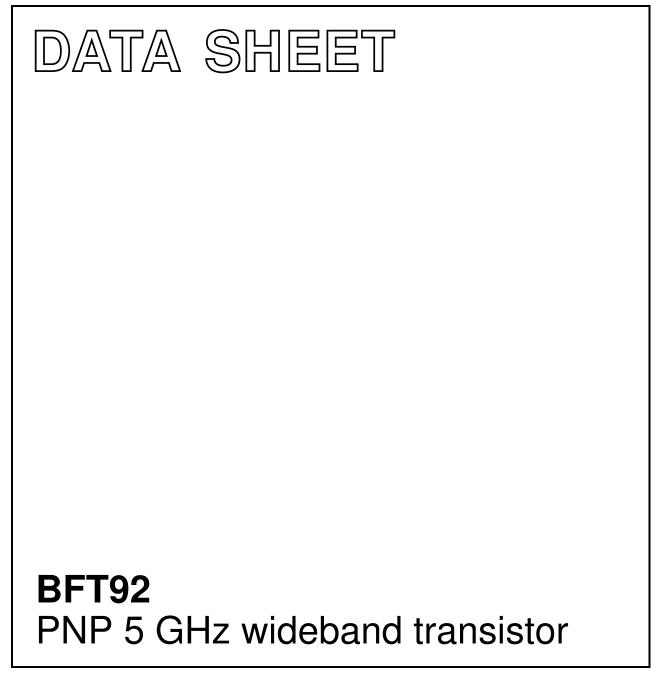


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DISCRETE SEMICONDUCTORS



Product specification

November 1992



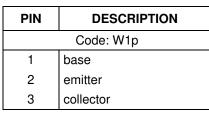
DESCRIPTION

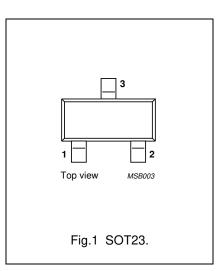
PNP transistor in a plastic SOT23 envelope.

It is primarily intended for use in RF wideband amplifiers, such as in aerial amplifiers, radar systems, oscilloscopes, spectrum analyzers, etc. The transistor features low intermodulation distortion and high power gain; due to its very high transition frequency, it also has excellent wideband properties and low noise up to high frequencies.

NPN complements are BFR92 and BFR92A.

PINNING





QUICK REFERENCE DATA

| SYMBOL | PARAMETER | CONDITIONS | TYP. | MAX. | UNIT |
|------------------|-------------------------------|---|------|------|------|
| V _{CBO} | collector-base voltage | open emitter | - | -20 | V |
| V _{CEO} | collector-emitter voltage | open base | _ | -15 | V |
| I _C | DC collector current | | - | -25 | mA |
| P _{tot} | total power dissipation | up to T _s = 95 °C; note 1 | _ | 300 | mW |
| f _T | transition frequency | $I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V}; f = 500 \text{ MHz}$ | 5 | - | GHz |
| C _{re} | feedback capacitance | $I_{C} = -2 \text{ mA}; V_{CE} = -10 \text{ V}; f = 1 \text{ MHz}$ | 0.7 | - | pF |
| G _{UM} | maximum unilateral power gain | $I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C | 18 | _ | dB |
| F | noise figure | $I_{C} = -5 \text{ mA}; V_{CE} = -10 \text{ V}; f = 500 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$ | 2.5 | - | dB |
| d _{im} | intermodulation distortion | $ I_{C} = -14 \text{ mA}; \text{ V}_{CE} = -10 \text{ V}; \text{ R}_{L} = 75 \Omega; \\ V_{o} = 150 \text{ mV}; \text{ T}_{amb} = 25 \text{ °C}; \\ f_{(p+q-r)} = 493.25 \text{ MHz} $ | -60 | _ | dB |

Note

1. T_s is the temperature at the soldering point of the collector tab.

BFT92

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|---------------------------|--------------------------------------|------|------|------|
| V _{CBO} | collector-base voltage | open emitter | - | -20 | V |
| V _{CEO} | collector-emitter voltage | open base | - | –15 | V |
| V _{EBO} | emitter-base voltage | open collector | _ | -2 | V |
| I _C | DC collector current | | _ | -25 | mA |
| I _{CM} | peak collector current 1 | f > 1 MHz | - | -35 | mA |
| P _{tot} | total power dissipation | up to T _s = 95 °C; note 1 | _ | 300 | mW |
| T _{stg} | storage temperature | | -65 | 150 | °C |
| Tj | junction temperature | | - | 175 | °C |

THERMAL RESISTANCE

| SYMBOL | PARAMETER | CONDITIONS | THERMAL RESISTANCE | | |
|---------------------|---|--------------------------------------|--------------------|--|--|
| R _{th j-s} | thermal resistance from junction to soldering point | up to T _s = 95 °C; note 1 | 260 K/W | | |

Note

1. T_s is the temperature at the soldering point of the collector tab.

BFT92

CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

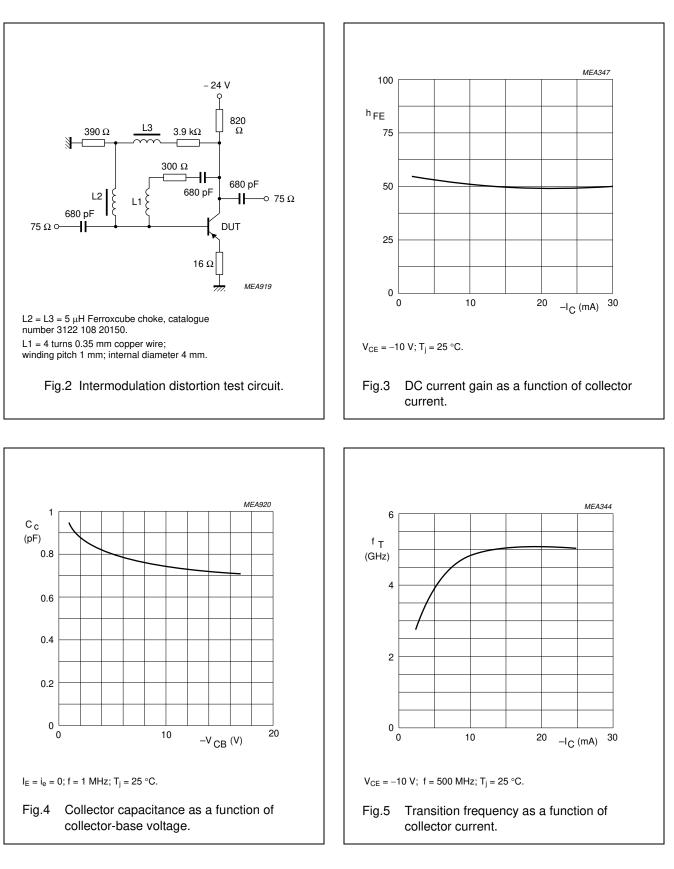
| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|------------------|--|--|------|------|------|------|
| I _{CBO} | collector cut-off current | $I_{E} = 0; V_{CB} = -10 V;$ | - | _ | -50 | nA |
| h _{FE} | DC current gain | $I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V}$ | 20 | 50 | - | |
| f _T | transition frequency | $I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz | - | 5 | - | GHz |
| C _c | collector capacitance | $I_E = i_e = 0; V_{CB} = -10 V; f = 1 MHz$ | - | 0.75 | - | pF |
| C _e | emitter capacitance | $I_{C} = i_{c} = 0; V_{EB} = -0.5 V; f = 1 MHz$ | - | 0.8 | - | pF |
| C _{re} | feedback capacitance | $I_{C} = -2 \text{ mA}; V_{CE} = -10 \text{ V}; f = 1 \text{ MHz}$ | - | 0.7 | _ | pF |
| G _{UM} | maximum unilateral power gain (note 1) | $I_{C} = -14 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C | - | 18 | - | dB |
| F | noise figure | $I_{C} = -5 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; T _{amb} = 25 °C | - | 2.5 | - | dB |
| Vo | output voltage | note 2 | - | 150 | - | mV |

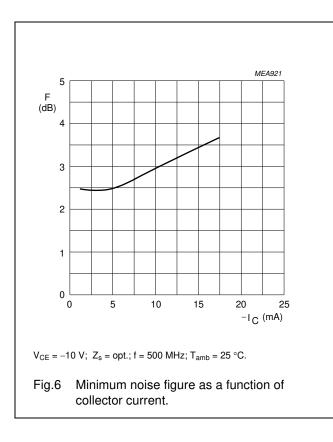
Notes

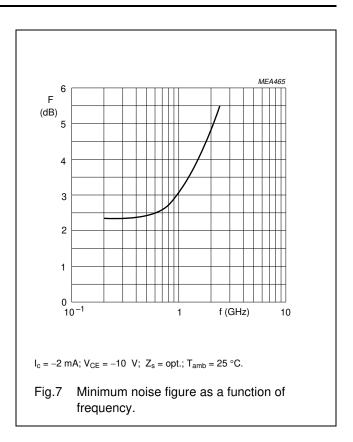
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB.$$

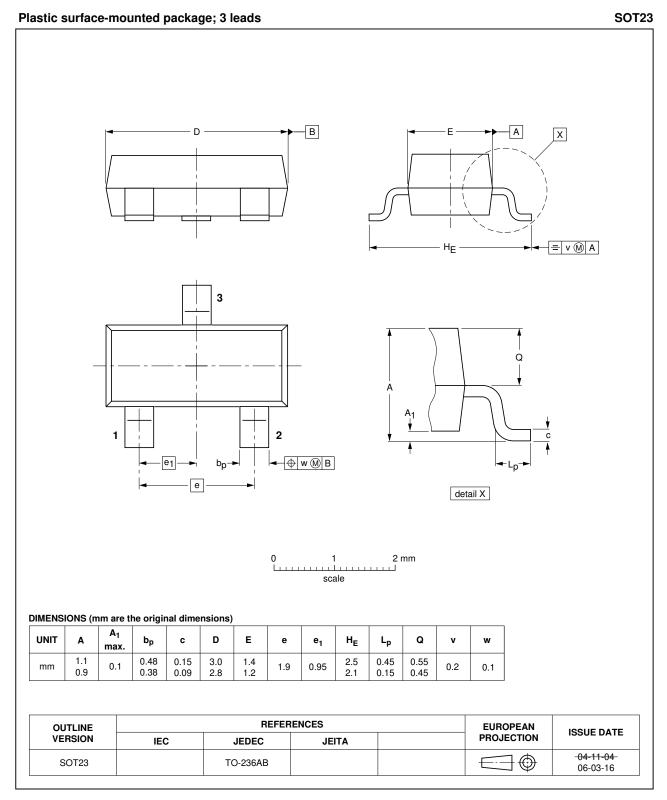
 $\begin{array}{ll} \text{2.} & d_{im} = -60 \; dB \; (\text{DIN } 45004B); \; I_C = -14 \; \text{mA}; \; V_{CE} = -10 \; V; \; R_L = 75 \; \Omega; \\ & V_p = V_o \; at \; d_{im} = -60 \; dB; \; f_p = 495.25 \; \text{MHz}; \\ & V_q = V_o \; -6 \; dB; \; f_q = 503.25 \; \text{MHz}; \\ & V_r = V_o \; -6 \; dB; \; f_r = 505.25 \; \text{MHz}; \\ & \text{measured at } f_{(p+q-r)} = 493.25 \; \text{MHz}. \end{array}$







PACKAGE OUTLINE



BFT92

DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|-----------------------------------|----------------------------------|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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Printed in The Netherlands

R77/02/pp10

Date of release: November 1992